Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6	(("20030102566") or ("20040043607") or ("6903443")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/06 17:40
L2	3325	((438/761) or (438/667) or (438/637) or (438/640)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/06 18:19
S1	1	US-6251488-$.DID. OR US-US6259962-$.DID. OR US-US6268584-$.DID. OR US-US639251-$.DID.	USPAT	OR	OFF	2004/08/04 19:44
S2	4	US-6251488-$.DID. OR US-6259962-$.DID. OR US-6268584-$.DID. OR US-6391251-$.DID.	USPAT	OR	OFF	2004/08/04 20:09
S3	0	20020171777-$.DID. OR 20030151167-$.DID.	US-PGPUB; USPAT	OR	OFF	2004/08/04 20:10
S4	2	"20020171777".pn. OR "20030151167".pn.	US-PGPUB; USPAT	OR	OFF	2004/08/04 20:11
S5	2	"20020171177".pn. OR "20030151167".pn.	US-PGPUB; USPAT	OR	OFF	2004/08/04 20:16
S6	506959	throughhole or through adj hole or via adj hole or viahole	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 17:02
S7	3018261	photopolymer or polymer or resin or epoxy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 14:45
S8	33758	laser near4 (cur$4 or harden$4 or consolidat$4 or ossif$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 14:49
S9	103	(throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur$4 or harden$4 or consolidat$4 or ossif$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/04 20:19

S10	103	((throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur$4 or harden$4 or consolidat$4 or ossif$4))) and (@ad < "20030916")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/04 20:19
S11	25	(throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur$4 or harden$4 or consolidat$4 or ossif$4)) same (photopolymer or polymer or resin or epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/04 20:20
S12	13	(throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near8 (photopolymer or polymer or resin or epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/04 20:34
S13	0	((throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near8 (photopolymer or polymer or resin or epoxy)) not ((throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur$4 or harden$4 or consolidat$4 or ossif$4)) same (photopolymer or polymer or resin or epoxy))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/04 20:35
S14	12	((throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur$4 or harden$4 or consolidat$4 or ossif$4)) same (photopolymer or polymer or resin or epoxy)) not ((throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near8 (photopolymer or polymer or resin or epoxy))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/04 20:35
S15	3022763	substrate or wafer or die or chip or ic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 14:57
S16	507324	throughhole or through adj hole or via adj hole or viahole	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 14:52

S17	0	trepn$4 same (throughhole or through adj hole or via adj hole or viahole) same (substrate or wafer or die or chip or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 14:37
S18	0	trepn$4 and (throughhole or through adj hole or via adj hole or viahole) and (substrate or wafer or die or chip or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 14:37
S19	0	trepn$4 and (throughhole or through adj hole or via adj hole or viahole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 14:34
S20	1617	trepan$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 17:02
S21	2	trepn$4 and (substrate or wafer or die or chip or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 14:35
S22	14	trepan$4 same (throughhole or through adj hole or via adj hole or viahole) same (substrate or wafer or die or chip or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 14:37
S23	3140914	photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 14:49
S24	4719	(throughhole or through adj hole or via adj hole or viahole) near2 (photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 14:49
S25	3938724	cur$4 or harden$4 or consolidat$4 or ossif$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 14:49
S26	210824	(photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 14:50

S27	965	((throughhole or through adj hole or via adj hole or viahole) near2 (photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4))) and ((photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 14:55
S28	2421605	edge or border or perimeter or circumferance	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 14:52
S29	4636315	throughhole or through adj hole or via adj hole or viahole or open$4 or recess or aperature	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 15:03
S30	86	(throughhole or through adj hole or via adj hole or viahole or open$4 or recess or aperature) same ((photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near4 (edge or border or perimeter or circumferance)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 14:56
S31	27	((throughhole or through adj hole or via adj hole or viahole or open$4 or recess or aperature) same ((photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near4 (edge or border or perimeter or circumferance)) and (substrate or wafer or die or chip or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 14:57
S32	3022763	substrate or wafer or die or chip or ic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 14:57

S33	27	((throughhole or through adj hole or via adj hole or viahole or open$4 or recess or aperature) same ((photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near4 (edge or border or perimeter or circumferance)) and (substrate or wafer or die or chip or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 15:03
S34	178	(throughhole or through adj hole or via adj hole or viahole or open$4 or recess or aperature) same ((photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4)) same (drill$4 or etch$4 or laser$4) near4 (throughhole or through adj hole or via adj hole or viahole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 15:06
S35	6715023	coat$4 or lin$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 15:07
S36	505	(throughhole or through adj hole or via adj hole or viahole) near4 (coat$4 or lin$4) near4 (photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 15:09
S37	369	(throughhole or through adj hole or via adj hole or viahole) near4 ((photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near4 (photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 15:13

S38	193	(throughhole or through adj hole or via adj hole or viahole) near4 ((photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near4 (photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) and (substrate or wafer or die or chip or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 15:11
S39	193	(throughhole or through adj hole or via adj hole or viahole) near4 ((photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near4 (photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) and (substrate or wafer or die or chip or ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 15:12
S40	24	(throughhole or through adj hole or via adj hole or viahole) near4 ((photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near4 (coat$4 or lin$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 15:14
S41	1617	trepan$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 17:02
S42	336075	drill$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 17:02
S43	507324	throughhole or through adj hole or via adj hole or viahole	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 17:03
S44	3503714	metal or copper or cvd	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 17:04

S45	120667	cvd	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 17:04
S46	0	trepan$4 near8 drill$4 same cvd near4 (metal or copper or cvd) near8 (throughhole or through adj hole or via adj hole or viahole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 17:05
S47	0	trepan$4 near8 drill$4 same cvd near8 (throughhole or through adj hole or via adj hole or viahole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 17:05
S48	0	trepan$4 near8 drill$4 and cvd near8 (throughhole or through adj hole or via adj hole or viahole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 17:05
S49	0	trepan$4 same drill$4 and cvd near8 (throughhole or through adj hole or via adj hole or viahole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 17:05
S50	454	trepan$4 same drill$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 17:05
S51	22	trepan$4 same drill$4 same (throughhole or through adj hole or via adj hole or viahole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 17:16
S52	30778	frustoconical	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 17:16
S53	304	frustoconical.ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/05 17:16
S54	2777	((438/761) or (438/667) or (438/637) or (438/640)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/06 18:19
S55	0	"200400112881".pn. and plat$4	USPAT	OR	ON	2004/08/05 19:46

S56	0	"200400112881".pn.	USPAT	OR	ON	2004/08/05 19:46
S57	0	"200400112881".pn.	US-PGPUB; USPAT	OR	ON	2004/08/05 19:47
S58	1	"20040112881".pn.	US-PGPUB; USPAT	OR	ON	2004/08/05 19:47
S59	1	"20040112881".pn. and plat$4	US-PGPUB; USPAT	OR	ON	2004/08/05 19:47